

SN54122, '123, '130, 'L122, 'L123, 'LS122, 'LS123 SN74122, '123, '130, 'LS122, 'LS123

Retriggerable Monostable Multivibrators

These d-c triggered multivibrators feature output pulse width control by three methods. The basic pulse time is programmed by selection of external resistance and capacitance values. The '122, 'L122, and 'LS122 have internal timing resistors that allow the circuits to be used with only an external capacitor, if so desired. Once triggered, the basic pulse width may be extended by retriggering the gated low-level-active (A) or high-level-active (B) inputs, or be reduced by use of the overriding clear.

The 'LS122 and 'LS123 are provided enough Schmitt hysteresis to ensure jitter-free triggering from the B input with transition rates as slow as 0.1 millivolt per nanosecond.

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
 - · Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

- D-C Triggered from Active-High or Active-Low Gated Logic Inputs
- Retriggerable for Very Long Output Pulses, Up to 100% Duty Cycle
- Overriding Clear Terminates Output Pulse
- '122 and 'LS122 Have Internal Timing Resistors

description

These d-c triggered multivibrators feature output pulse-duration control by three methods. The basic pulse time is programmed by selection of external resistance and capacitance values (see typical application data). The '122 and 'LS122 have internal timing resistors that allow the circuits to be used with only an external capacitor, if so desired. Once triggered, the basic pulse duration may be extended by retriggering the gated low-level-active (A) or high-level-active (B) inputs, or be reduced by use of the overriding clear. Figure 1 illustrates pulse control by retriggering and early clear.

The 'LS122 and 'LS123 are provided enough Schmitt hysteresis to ensure jitter-free triggering from the B input with transition rates as slow as 0.1 millivolt per nanosecond.

The $R_{\mbox{\scriptsize int}}$ in nominall 10 $k\Omega$ for '122 and 'LS122.

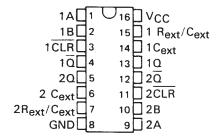
SN54122, SN54LS122...J OR W PACKAGE SN74122...N PACKAGE SN74LS122...D OR N PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)

A1 🗆	1	J 14		Vcc
A2 [2	13		R _{ext} /C _{ext}
B1 □	3	12	Þ	NC
B2 ☐	4	11		C _{ext}
CLR	5	10		NC
₫□	6	9		Rint
GND□	7	8	þ	Q

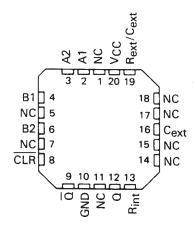
NOTES: 1. An external timing capacitor may be connected between C_{ext} and $\text{Re}_{\text{xt}}/C_{\text{ext}}$ (positive).

- To use the internal timing resistor of '122 or 'LS122, connect R_{int} to V_{CC}.
- For improved pulse duration accuracy and repeatability, connect an external resistor between R_{ext}/Ce_{xt} and V_{CC} with R_{int} open-circuited.
- To obtain variable pulse durations, connect an external variable resistance between R_{int} or R_{ext}/C_{ext} and VCC.

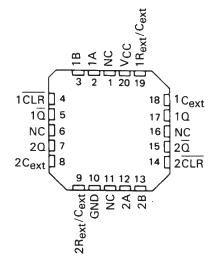
SN54123, SN54130, SN54LS123 . . . J OR W PACKAGE SN74123, SN74130 . . . N PACKAGE SN74LS123 . . . D OR N PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)



SN54LS122 . . . FK PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)



SN54LS123 . . . FK PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)



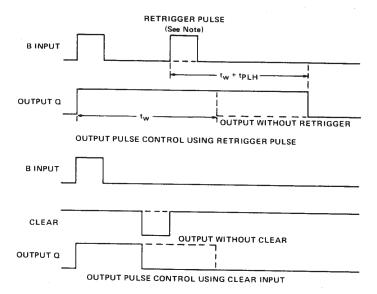
NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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description (continued)



NOTE: Retrigger pulses starting before 0.22 C_{ext} (in picofrads) nanoseconds after the initial trigger pulse will be ignored and the output duration will remain unchanged.

FIGURE 1-TYPICAL INPUT/OUTPUT PULSES

'122, 'L\$122 **FUNCTION TABLE**

	INP	JTS			OUT	UTS
CLEAR	Α1	A2	В1	B2	Q	ā
L	Х	X	Х	Х	L	Н
×	н	Н	Х	×	L†	нŤ
×	Х	X	L	Х	L†	н†
×	Х	Х	Х	L	L†	нŤ
н	L	Х	1	Н	Λ	U
н	L	Χ	Н	1	Л	IJ
н	Х	L	↑	Н	7.	v
н	Х	L	Н	†	Л	U
н	Н	1	Н	Н	V	IJ
н	1	\downarrow	Н	н	V	J.
н	1	Н	Н	н	Л	u
1	L	X	Н	н	7	U
_ †	×	L	Н	н	7	v

'123, '130, 'LS123 **FUNCTION TABLE**

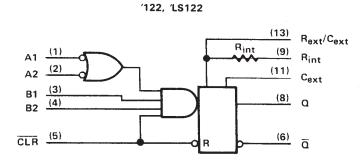
INPL	JTS		ουτι	PUTS
CLEAR	Α	В	α	ā
L	Х	Х	L	Н
×	н	X	L†	нŤ
×	х	L	L†	нŤ
Н	L	†	Л	U
Н	ţ	Н	Л	T
1	L	Н	7	v

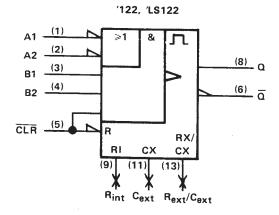
See explanation of function tables on page

† These lines of the functional tables assume that the indicated steady-state conditons at the A and B inputs have been set up long enough to complete any pulse started before the set up.

logic diagram (positive logic)

logic symbol†

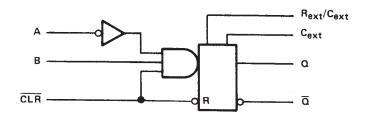




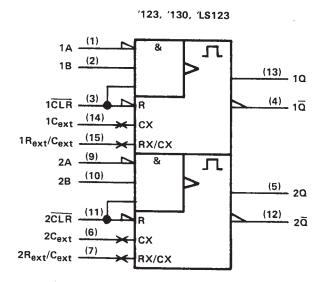
 $R_{\mbox{\scriptsize int}}$ is nominally 10 $k\Omega$ for '122 and 'LS122

logic diagram (positive logic) (each multivibrator)

'123, '130, 'LS123



logic symbol†



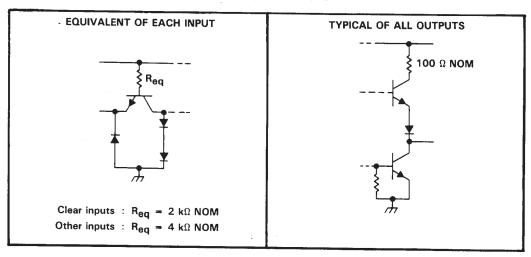
Pin numbers shown are for D, J, N, and W packages.

[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

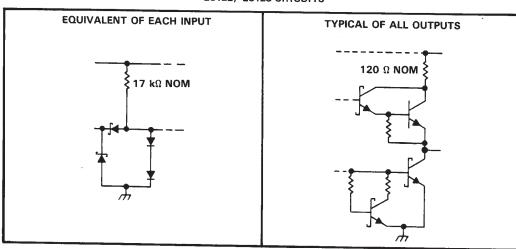
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schematics of inputs and outputs

'122, '123, '130 CIRCUITS



'LS122, 'LS123 CIRCUITS



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7.1/
Input voltage: '122, '123, '130	/ V
(1912) (1912)	5.5 V
'LS122, 'LS123	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
Short-1	000 + 7000
Storage temperature range	0°C to /0°C
Storage temperature range	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

		SN54'			SN74'		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			800	μА
Low-level output current, IOL			16			16	mA
Pulse duration, t _W	40			40			ns
External timing resistance, R _{ext}	5		25	5		50	kΩ
External capacitance, C _{ext}		restrict			restrict		1,72
Wiring capacitance at Rext/Cext terminal			50	140	710311101	50	
Operating free-air temperature, TA	-55		125	0		70	pF °C

electrical characteristics over recommended free-air operating temperature range (unless otherwise noted)

	PARAMETER		TEST CO	NDITIONS†		122			123, 113	30	
			120100	- TONG	MIN	TYP#	MAX	MIN	TYP±	MAX	UNIT
VIH	High-level input voltage				2	· · · ·		2			V
VIL	Low-level input voltage						0.8			0.8	l v
VIK	Input clamp voltage		VCC = MIN,	I _I = -12 mA			-1.5			-1.5	V
Vон	High-level output voltage		V _{CC} = MIN, See Note 5	$I_{OH} = -800 \mu\text{A},$	2.4	3.4	1.5	2.4	3.4	-1.5	V
VoL	Low-level output voltage		V _{CC} = MIN, See Note 5	IOL = 16 mA,		0.2	0.4		0.2	0.4	V
11	Input current at maximum i	nput voltage	V _{CC} = MAX,	V _I = 5.5 V			1			1	mA
Ιн	High-level input current	Data inputs	V _{CC} = MAX,	V 2 4 V			40	_		40	1117
		Clear input	VCC - WAX,	V - 2,4 V			80			80	μΑ
HE	Low-level input current	Data inputs	V _{CC} = MAX,	V ₁ = 0.4.V			-1.6			-1.6	
		Clear input	VCC WAX,	V - 0.4 V			-3.2			-3.2	mA
los	Short-circuit output current	3	VCC = MAX,	See Note 5	-10		-40	-10		-40	mΑ
Icc	Supply current (quiescent o	r triggered)	V _{CC} = MAX,	See Notes 6 and 7		23	36		46	66	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 5. Ground C_{ext} to measure V_{OH} at Q, V_{OL} at \overline{Q} , or I_{OS} at Q. C_{ext} is open to measure V_{OH} at \overline{Q} , V_{OL} at Q, or I_{OS} at \overline{Q} .

6. Quiescent ICC is measured (after clearing) with 4.5 V applied to all clear and A inputs, B inputs grounded, all outputs open and R_{ext} = 25 k Ω . R_{int} of '122 is open.

7. ICC is measured in the triggered state with 2.4 V applied to all clear and B inputs, A inputs grounded, all outputs open, $C_{ext} = 0.02 \,\mu\text{F}$, and $R_{ext} = 25 \,\text{k}\Omega$. R_{int} of '122 is open.

switching characteristics, VCC = 5 V, TA = 25°C, see note 8

DADAMETER	FROM	то			122, ′1	30		′123	-		
PARAMETER¶	(INPUT)	(OUTPUT)	TEST CON	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
^t PLH	Α	Q				22	33		22	33	
	В					19	28		19	28	ns
^t PHL	A	ā	C _{ext} = 0,	$R_{ext} = 5 k\Omega$,		30	40		30	40	
	В		C ₁ = 15 pF,	$R_1 = 400 \Omega$		27	36		27	36	ns
tPHL	Clear	<u> </u>	°	11 400 32		18	27		18	27	
tPLH t						30	40		30	40	ns
t _{WQ} (min)	A or B	Q	_			45	65		45	76	ns
^t wQ	A or B	a	C _{ext} = 1000 pF, C _L = 15 pF,	$R_{ext} = 10 \text{ k}\Omega$, $R_L = 400 \Omega$	3.08	3.42	3.76	2.76	3.03	3.37	μs

TtpLH = propagation delay time, low-to-high-level output

NOTE 8: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§] Not more than one output should be shorted at a time.

tpHL = propagation delay time, high-to-low-level output

 t_{WQ} = duration of pulse at output Q.

SN54LS122, SN54LS123, SN74LS122, SN74LS123 RETRIGGERABLE MONOSTABLE MULTIVIBRATORS

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recommended operating conditions

		SN54LS'			SN74LS'			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	٧	
High-level output current, IOH			-400			-400	μА	
Low-level output current, IOL			4			8	mA	
Pulse duration, t _W	40			40			ns	
External timing resistance, R _{ext}	5		180	5		260	kΩ	
External capacitance, C _{ext}	N	o restric	tion	No	restrict	tion		
Wiring capacitance at R _{ext} /C _{ext} terminal			50			50	pF	
Operating free-air temperature, TA	-55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEC	T CONDITIONS†			SN54LS	3'		SN74LS	,	
	FARAMETER	1 53	T CONDITIONS		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage				2			2			V
V_{1L}	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I _I = -18 mA				-1.5			-1.5	V
Vон	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V, I _{OH} = -400 μA		2.5	3.5		2.7	3.5		V
VOL	Low-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4		0.25 0.35	0.4	V
l ₁	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 7 V	I IOL - 8 IIIA			0.1		0.35	0.5	mA
ΊΗ	High-level input current	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μА
IL	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V				-0.4			-0.4	mA
los	Short-circuit output current§	V _{CC} = MAX			-20		-100	-20		-100	mA
lcc	Supply current (quiescent or triggered)	V _{CC} = MAX,	See Note 13	'LS122 'LS123		6 12	11 20		6 12	11 20	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 12. To measure VOH at Q, VOL at Q, or IOS at Q, ground Rext/Cext, apply 2 V to B and clear, and pulse A from 2 V to 0 V.

switching characteristics, VCC = 5 V, TA = 25°C (see note 8)

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CON	TEST CONDITIONS				UNIT
tout	Α	α				23	33	
^t PLH	В	u u				23	44	ns
tPHL	Α	۵	C -0	D - 5 1:0		32	45	
PHL	В	ď	C _{ext} = 0, C _L = 15 pF,	$R_{ext} = 5 k\Omega$, $R_{L} = 2 k\Omega$		34	56	ns
tPHL.	Clear	Q	CL = 15 pr,	H = 2 K32		20	27	
^t PLH	Cieal	ā				28	45	ns
t _{wQ} (min)	A or B	Q				116	200	ns
twQ	A or B	Q	C _{ext} = 1000 pF, C _L = 15 pF,	$R_{ext} = 10 k\Omega$, $R_L = 2 k\Omega$	4	4.5	5	μs

TtpLH = propagation delay time, low-to-high-level output



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§]Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

^{13.} With all outputs open and 4.5 V applied to all data and clear inputs. ICC is measured after a momentary ground, then 4.5 V, is applied to A or B inputs.

tpHL = propagation delay time, high-to-low-level output

 t_{WQ} = duration of pulse at output Q.

NOTE 8: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA FOR '122, '123, '130

For pulse durations when $C_{ext} \leq 1000$ pF, see Figure 4.

The output pulse duration is primarily a function of the external capacitor and resistor. For $C_{ext} > 1000 \ pF$, the output pulse duration (t_W) is defined as:

$$t_W = K \cdot R_T \cdot C_{ext} \left(1 + \frac{0.7}{R_T} \right)$$

where

K is 0.32 for '122, 0.28 for '123 and '130

 $R_{\mbox{\scriptsize T}}$ is in $k\Omega$ (internal or external timing resistance.)

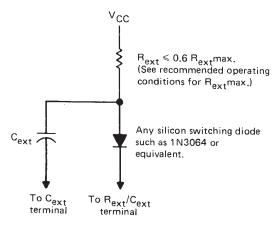
Cext is in pF

tw is in ns

To prevent reverse voltage across C_{ext} , it is recommended that the method shown in Figure 2 be employed when using electrolytic capacitors and in applications utilizing the clear function. In all applications using the diode, the pulse duration is:

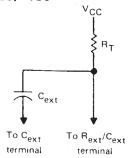
$$t_{W} = K_{D} \cdot R_{T} \cdot C_{ext} \left(1 + \frac{0.7}{R_{T}} \right)$$

Kp is 0.28 for '122, 0.25 for '123 and '130



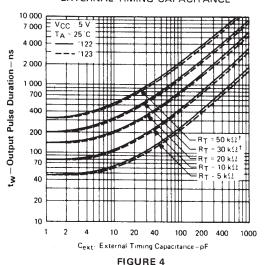
TIMING COMPONENT CONNECTIONS WHEN $C_{ext} \geq 1000 \; \text{pF AND CLEAR IS USED}$ FIGURE 2

Applications requiring more precise pulse durations (up to 28 seconds) and not requiring the clear feature can best be satisfied with the '121.



TIMING COMPONENT CONNECTIONS FIGURE 3

TYPICAL OUTPUT PULSE DURATION vs
EXTERNAL TIMING CAPACITANCE



[†]These values of resistance exceed the maximum recommended for use over the full temperature range of the SN54' circuits.

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TYPICAL APPLICATION DATA FOR 'LS122, 'LS123

The basic output pulse duration is essentially determined by the values of external capacitance and timing resistance. For pulse durations when Cext≤1000 pF, use Figure 6, or use Figure 7 where the pulse duration may be defined as:

$$t_W = K \cdot R_T \cdot C_{ext}$$

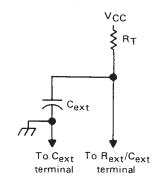
When $C_{ext} \ge 1 \mu F$, the output pulse width is defined

$$t_W = 0.33 \cdot R_T \cdot C_{ext}$$

For the above two equations, as applicable;

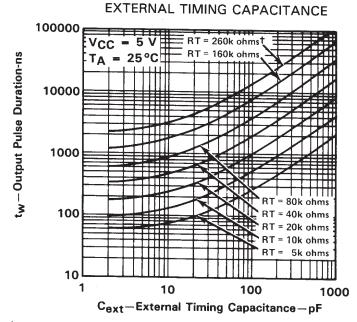
K is multiplier factor, see Figure 7 $R_{\mbox{\scriptsize T}}$ is in $k\Omega$ (internal or external timing resistance) Cext is in pF tw is in ns

For maximum noise immunity, system ground should be applied to the Cext node, even though the Cext node is already tied to the ground lead internally. Due to the timing scheme used by the 'LS122 and 'LS123. a switching diode is not required to prevent reverse biasing when using electolytic capacitors.



TIMING COMPONENT CONNECTIONS FIGURE 5

'LS122, 'LS123 TYPICAL OUTPUT PULSE DURATION



[†]This value of resistance exceeds the maximum recommended for use over the full temperature range of the SN54LS circuits.

FIGURE 6



TYPICAL APPLICATION DATA FOR 'LS122, 'LS123†



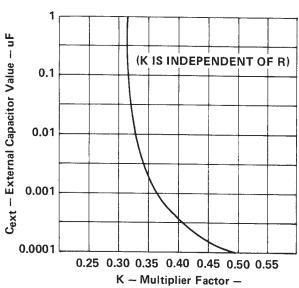
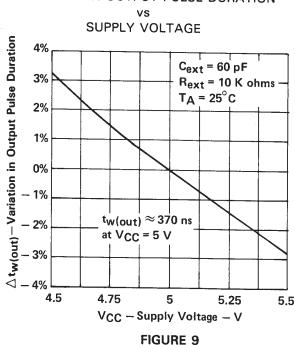
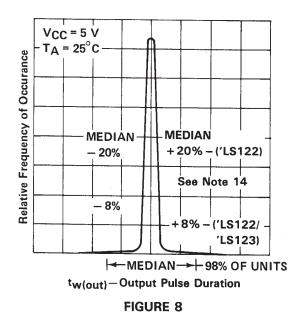


FIGURE 7

VARIATION IN OUTPUT PULSE DURATION



DISTRIBUTION OF UNITS vs OUTPUT PULSE DURATION



VARIATION IN OUTPUT PULSE DURATION

vs FREE-AIR TEMPERATURE

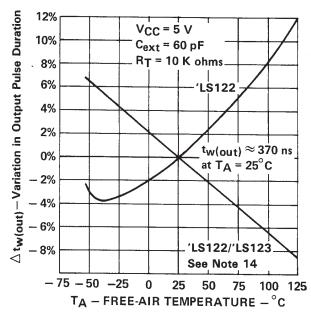


FIGURE 10

NOTE 14: For the 'LS122, the internal timing resistor, R_{int} was used. For the 'LS122/123, an external timing resistor was used for R_T.

†Data for temperatures below 0°C and above 70°C and for suply voltages below 4.75 V and above 5.25 V are applicable for SN54LS122 and SN54LS123 only.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-7603901VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-7603901VFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7603901EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
7603901FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/01203BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/31401B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/31401BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/31401BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54122J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54123J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS123J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN74122N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74123N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74123N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74123NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS122D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS122N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS122NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS122NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122NSRE4	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS122NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS123D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS123DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS123DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS123DR	ACTIVE	SOIC	D	16	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM
		-						

PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74LS123DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS123DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS123J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS123N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS123N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS123NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS123NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS123NSRG4	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54122J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54123J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54123W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS123FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS123J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS123W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS122DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS122NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS123DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS123NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

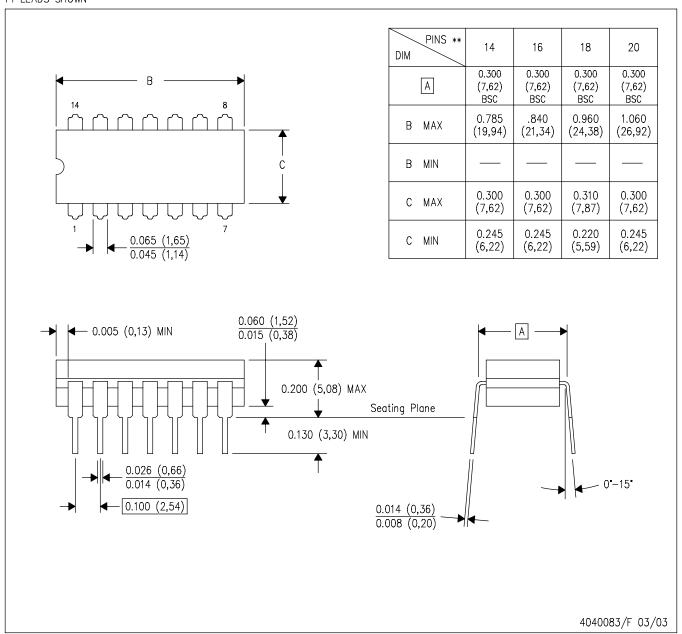




*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS122DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS122NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LS123DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS123NSR	SO	NS	16	2000	346.0	346.0	33.0

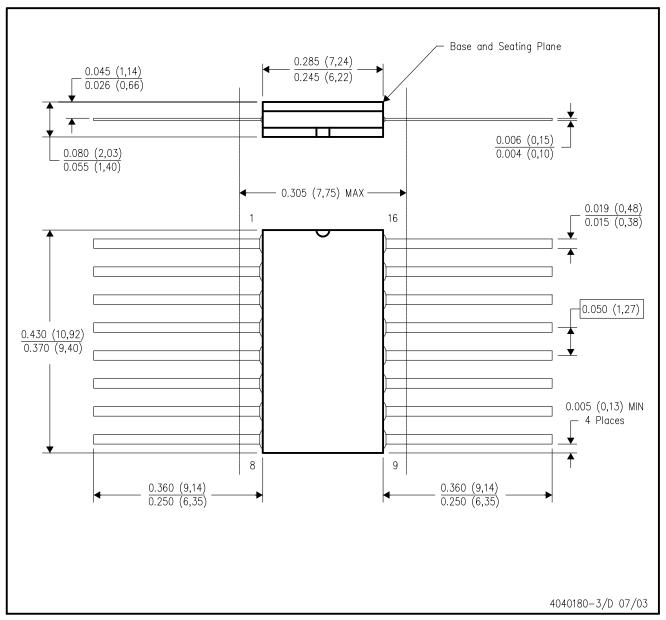
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



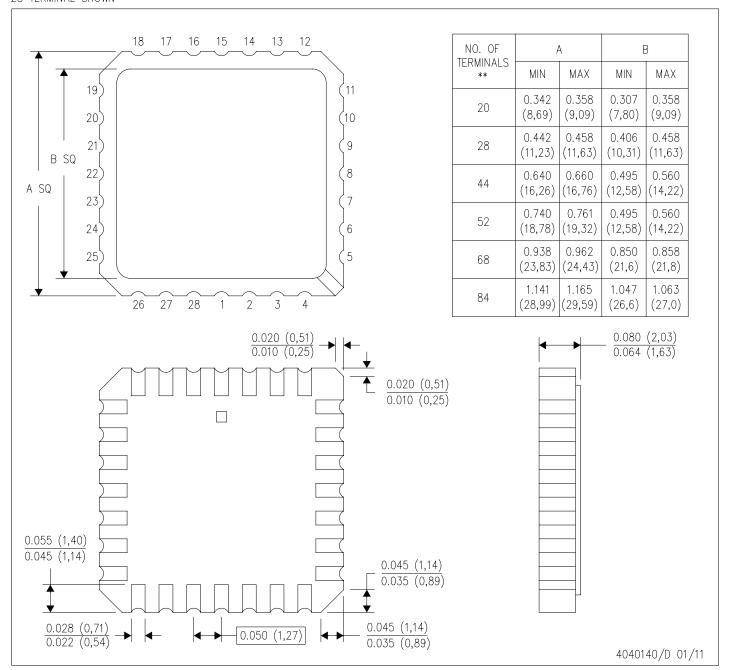
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



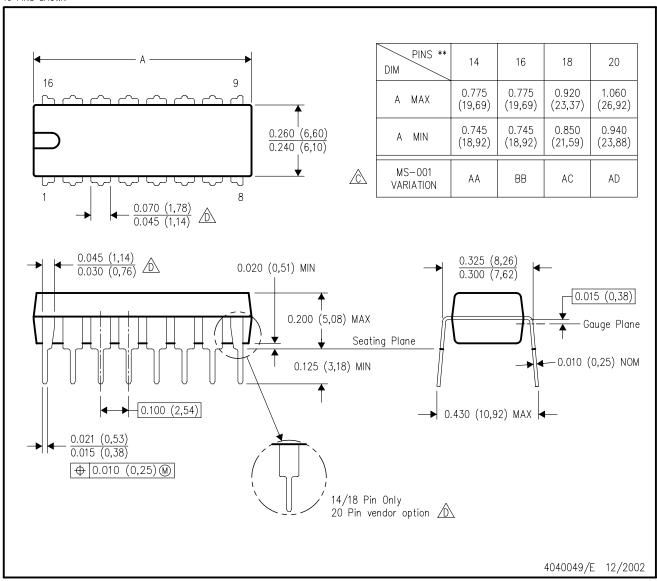
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

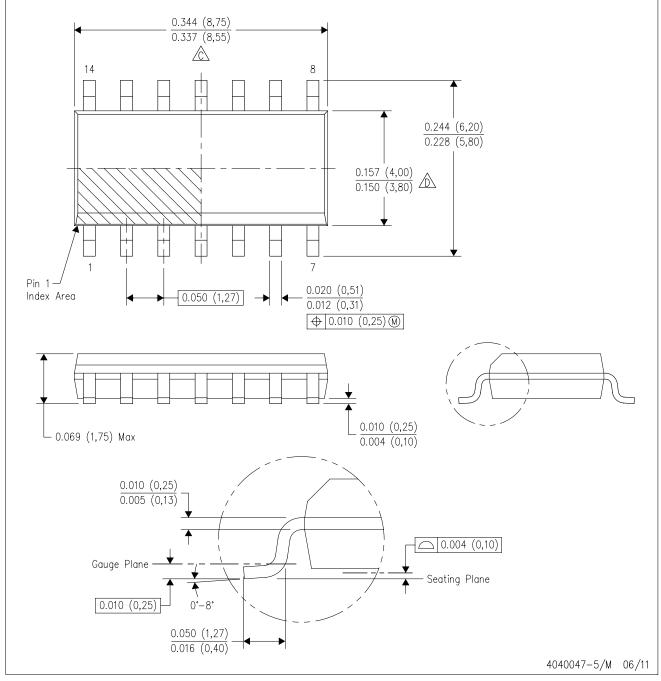


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

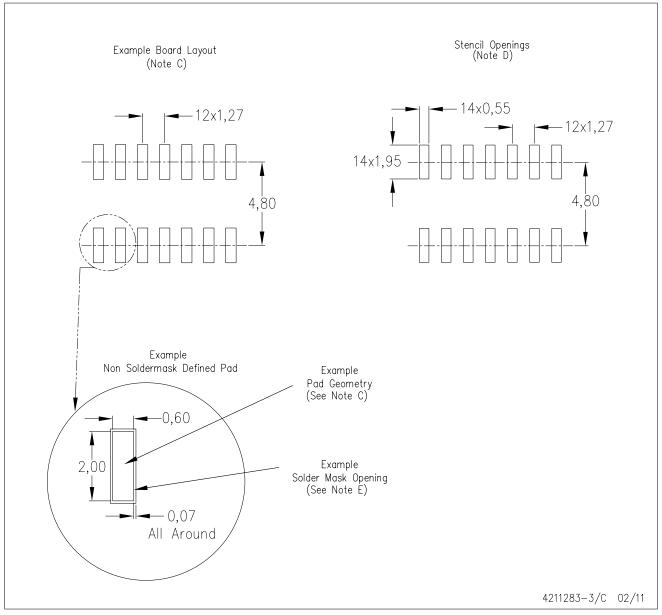


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

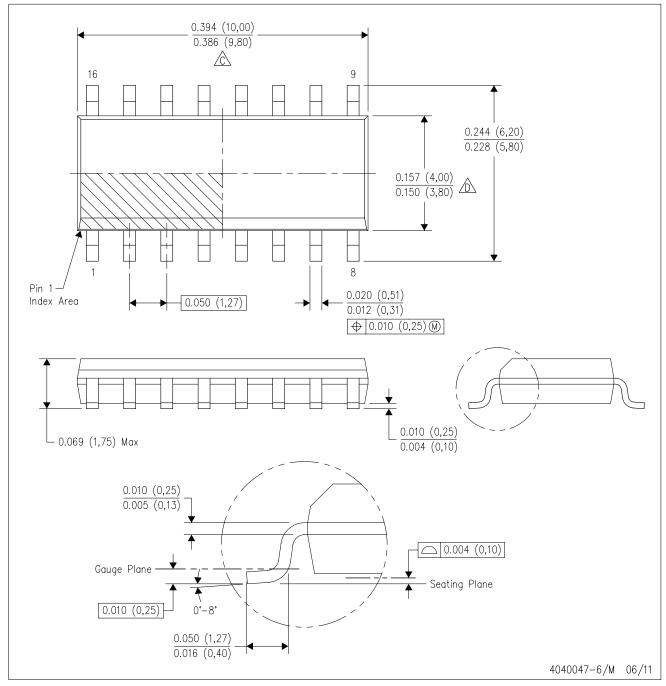


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE

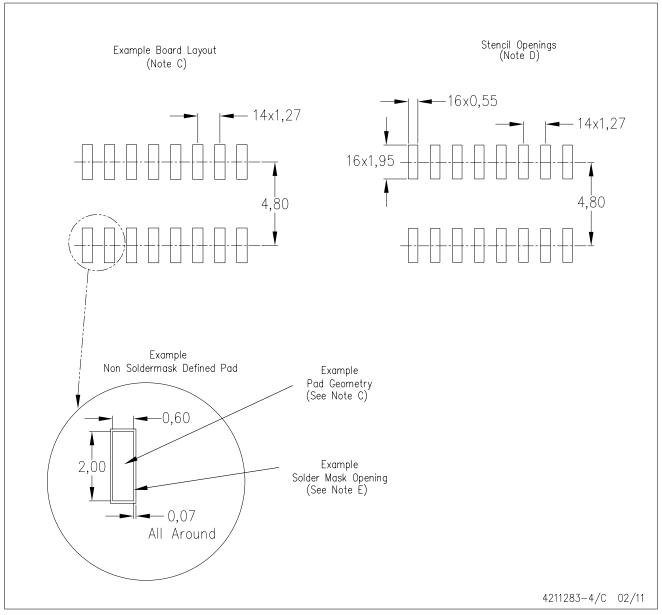


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



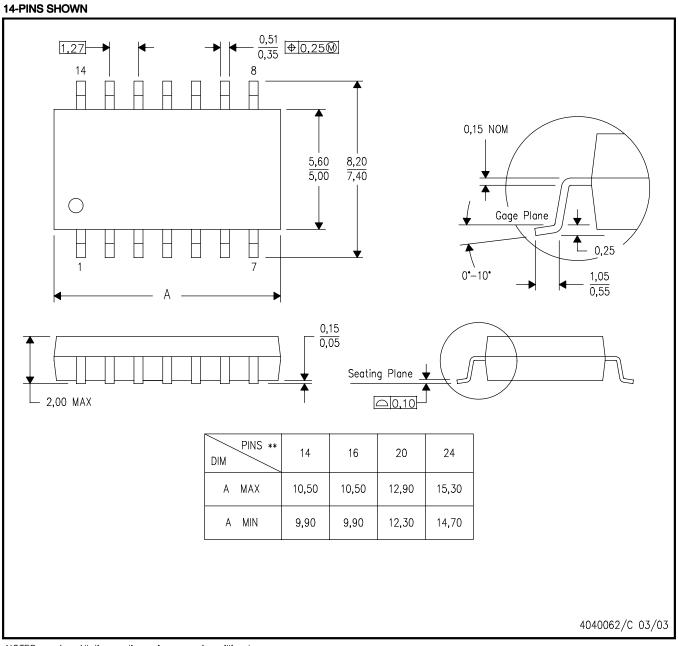
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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